

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 5,397,432
DATED : March 10, 1995
INVENTOR(S) : Konno, et. Al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 11, line 39, delete "or" insert therefor --and --
Column 10-11, Table 1, ~~insert symbols~~ attached Table 1.

~~See Attached Sheet~~

Table 1

Conditions	Amount of residual chlorine μm g/cm ² 10 ¹⁵ atoms/cm ²	After-corrosion	Symbols shown in Fig. 9
① Etching only	0.92±0.06	16.0±1.0	Large ○
② Downflow ashing using O ₂ after ①	0.89±0.06	15.5±1.0	Large ●
③ Downflow ashing using O ₂ +CF ₄ after ①	0.54±0.03	9.3±0.4	Small ■
④ Downflow ashing using O ₂ +H ₂ O after ①	0.23±0.03	4.0±0.5	No ◇
⑤ Exposure to H ₂ O after ② (30sec)	0.51±0.02	8.7±0.3	Small ▲
⑥ Exposure to H ₂ O after ② (90sec)	0.48±0.01	8.1±0.2	Small ▲
⑦ Exposure to H ₂ O after ② (180sec)	0.45±0.04	7.6±0.7	Small ▲
⑧ Downflow treatment using H ₂ O after ② (30sec)	0.28±0.01	4.7±0.2	None △
⑨ Downflow treatment using H ₂ O after ② (90sec)	0.15±0.00	2.5±0.0	No △
⑩ Downflow treatment using H ₂ O after ② (180sec)	0.11±0.01	1.9±0.1	No △
⑪ Downflow treatment using H ₂ after ② (30sec)	0.68±0.01	11.8±0.2	Small ▽
⑫ Downflow treatment using H ₂ after ② (90sec)	0.68±0.01	11.7±0.1	Small ▽
⑬ Downflow treatment using H ₂ after ② (180sec)	0.64±0.01	11.1±0.2	Small ▽

Exposure to H₂O: heated at 120°C in water vapor at 0.1 Torr.